Erratum

Cross-Interaction of Interfacial Reactions in Ni (Au/Ni/Cu)-SnAg-Cu Solder Joints during Reflow Soldering and Thermal Aging

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The phase diagram in Fig. 3 from our manuscript was determined by Zeng et al.¹ The original work should have been cited, and the author sincerely apologizes for this unintentional error.

REFERENCE

- 1 K. Zeng, V. Vuorinen, and J. Kivilahti, *IEEE Trans. Electron. Packaging Manuf.* 25, 162 (2002).